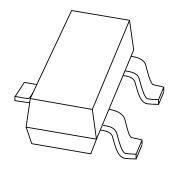
# **DISCRETE SEMICONDUCTORS**

# DATA SHEET



# PMBT4401 NPN switching transistor

Product data sheet Supersedes data of 1999 Apr 15 2004 Jan 21



# **NPN** switching transistor

**PMBT4401** 

#### **FEATURES**

- High current (max. 600 mA)
- Low voltage (max. 40 V).

## **APPLICATIONS**

• Industrial and consumer switching applications.

### **DESCRIPTION**

NPN switching transistor in a SOT23 plastic package. PNP complement: PMBT4403.

### **MARKING**

TYPE NUMBER	MARKING CODE <sup>(1)</sup>			
PMBT4401	*2X			

#### Note

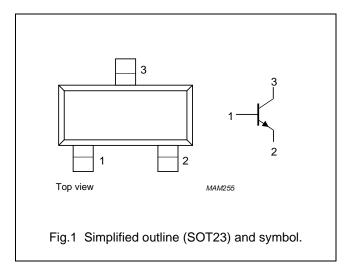
1. \* = p: Made in Hong Kong.

\* = t : Made in Malaysia.

## \* = W : Made in China.

#### **PINNING**

PIN	DESCRIPTION
1	base
2	emitter
3	collector



## **ORDERING INFORMATION**

TYPE	PACKAGE					
NUMBER	NAME	DESCRIPTION	VERSION			
PMBT4401	-	plastic surface mounted package; 3 leads	SOT23			

## **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	60	V
V <sub>CEO</sub>	collector-emitter voltage	open base	_	40	٧
V <sub>EBO</sub>	emitter-base voltage	open collector	_	6	٧
I <sub>C</sub>	collector current (DC)		_	600	mA
I <sub>CM</sub>	peak collector current		_	800	mA
I <sub>BM</sub>	peak base current		_	200	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1	_	250	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C

## Note

1. Transistor mounted on an FR4 printed-circuit board.

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# NPN switching transistor

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## THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th (j-a)</sub>	thermal resistance from junction to ambient	note 1	500	K/W

### Note

1. Transistor mounted on an FR4 printed-circuit board.

## **CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I <sub>CBO</sub>	collector-base cut-off current	I <sub>E</sub> = 0; V <sub>CB</sub> = 60 V		50	nA
I <sub>EBO</sub>	emitter-base cut-off current	I <sub>C</sub> = 0; V <sub>EB</sub> = 6 V	_	50	nA
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = 1 V; (see Fig.2)			
		$I_C = 0.1 \text{ mA}$	20	_	
		I <sub>C</sub> = 1 mA	40	_	
		I <sub>C</sub> = 10 mA	80	_	
		I <sub>C</sub> = 150 mA; note 1	100	300	
		I <sub>C</sub> = 500 mA; V <sub>CE</sub> = 2 V; note 1	40	_	
V <sub>CEsat</sub>	collector-emitter saturation	I <sub>C</sub> = 150 mA; I <sub>B</sub> = 15 mA; note 1	_	400	mV
	voltage	I <sub>C</sub> = 500 mA; I <sub>B</sub> = 50 mA; note 1	_	750	mV
V <sub>BEsat</sub>	base-emitter saturation voltage	I <sub>C</sub> = 150 mA; I <sub>B</sub> = 15 mA; note 1	_	950	mV
		I <sub>C</sub> = 500 mA; I <sub>B</sub> = 50 mA; note 1	_	1.2	V
C <sub>c</sub>	collector capacitance	I <sub>E</sub> = I <sub>e</sub> = 0; V <sub>CB</sub> = 5 V; f = 1 MHz	_	8	pF
C <sub>e</sub>	emitter capacitance	$I_C = I_c = 0$ ; $V_{EB} = 500 \text{ mV}$ ; $f = 1 \text{ MHz}$	_	30	pF
f <sub>T</sub>	transition frequency	I <sub>C</sub> = 20 mA; V <sub>CE</sub> = 10 V; f = 100 MHz	250	_	MHz
Switching t	imes (between 10% and 90% leve	ls); (see Fig.3)		•	
t <sub>on</sub>	turn-on time	I <sub>Con</sub> = 150 mA; I <sub>Bon</sub> = 15 mA;	_	35	ns
t <sub>d</sub>	delay time	$I_{Boff} = -15 \text{ mA}$	_	15	ns
t <sub>r</sub>	rise time		_	20	ns
t <sub>off</sub>	turn-off time		_	250	ns
t <sub>s</sub>	storage time		_	200	ns
t <sub>f</sub>	fall time		_	60	ns

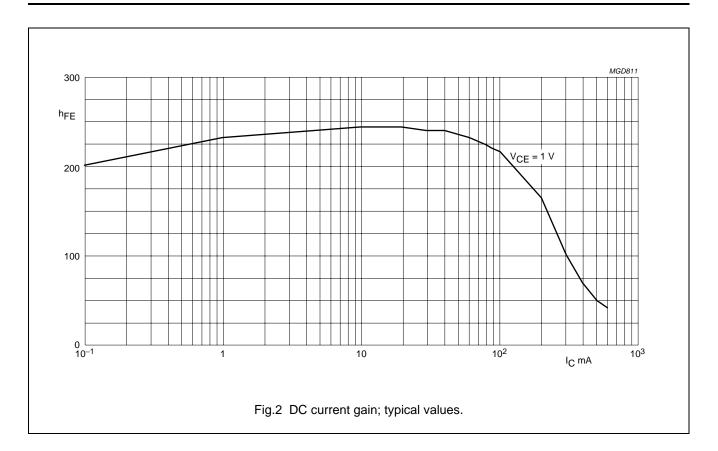
### Note

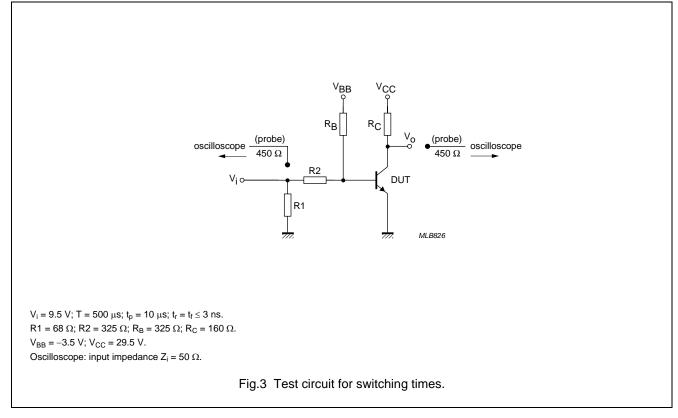
1. Pulse test:  $t_p \le 300~\mu s;~\delta \le 0.02.$ 

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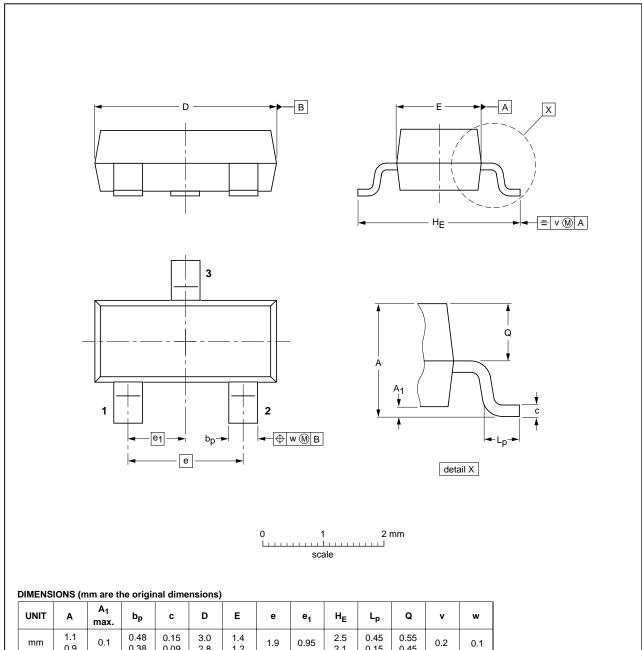
# NPN switching transistor

# PMBT4401

SOT23

## **PACKAGE OUTLINE**

## Plastic surface-mounted package; 3 leads



UNIT	Α	A <sub>1</sub> max.	bp	С	D	E	е	e <sub>1</sub>	HE	Lp	Q	v	w
mm	1.1 0.9	0.1	0.48 0.38	0.15 0.09	3.0 2.8	1.4 1.2	1.9	0.95	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1

OUTLINE		REFERENCES EUROPEAN ISSUE				ISSUE DATE
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT23		TO-236AB				<del>04-11-04</del> 06-03-16

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# NPN switching transistor

**PMBT4401** 

#### **DATA SHEET STATUS**

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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## **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

### **Contact information**

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